

Title (en)

Device for emplacing slices obtained by sawing of a block in storage elements

Title (de)

Vorrichtung für das Einlegen von durch Zersägen eines Rohlings erhaltenen Wafern in Aufbewahrungselemente

Title (fr)

Dispositif pour la mise en éléments de stockage de tranches obtenues par sciage d'un bloc

Publication

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Application

EP 97105331 A 19970329

Priority

CH 95696 A 19960416

Abstract (en)

[origin: EP0802028A2] The method involves placing the wafers (2) of a cut block (1) attached b a heel section (3) to s cutting support (4,5). A cutting station (6-8) has a cutter (7,15) to cut the heel and a drive (6) moves the wafers with respect to the cutter to present the wafers individually to a cutter to detach the wafers one by one from the heel sections. A collector (9,10) collects each detached wafer and places it in an empty case of the cassette. There can be a support plate (4) on which the cut block is placed and which is mounted on the cutter base.

IPC 1-7

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IPC 8 full level

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CPC (source: EP)

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